

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT4241070

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT	
<b>CONVEYING PARTY DATA</b>		
	<b>Name</b>	<b>Execution Date</b>
	BERNHARD STERING	12/13/2016
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<b>City:</b>	UNTERPREMSTAETTEN	
<b>State/Country:</b>	AUSTRIA	
<b>Postal Code:</b>	8141	
<b>PROPERTY NUMBERS Total: 1</b>		
	<b>Property Type</b>	<b>Number</b>
	Application Number:	15313489
<b>CORRESPONDENCE DATA</b>		
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<b>ATTORNEY DOCKET NUMBER:</b>	090922-0565	
<b>NAME OF SUBMITTER:</b>	JOHN D. MAGLUYAN, REG. NO. 56,867	
<b>SIGNATURE:</b>	/John D. Magluyan/	
<b>DATE SIGNED:</b>	01/24/2017	
<b>Total Attachments: 2</b>		
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source=090922-0565Assignment#page2.tif		

Docket No.: 090922-0565

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

(1) Bernhard STERING	(4) _____
(2) _____	(5) _____
(3) _____	(6) _____

who have made a certain new and useful invention, hereby sell, assign and transfer unto

ams AG  
Schloss Premstaetten  
Tobelbader Str. 30  
8141 Unterpremstaetten  
AUSTRIA

and its successors, assigns and legal representatives (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

DICING METHOD FOR WAFER-LEVEL PACKAGING AND SEMICONDUCTOR  
CHIP WITH DICING STRUCTURE ADAPTED FOR WAFER-LEVEL PACKAGING

for which an application for United States Letters Patent was filed on November 22, 2016, and identified by United States Application No. 15/313,489;

and the undersigned hereby authorize and request the registered practitioners of McDermott Will & Emery LLP to insert the filing date and application number of said application as necessary;

and the undersigned hereby authorize and request the United States Commissioner for Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, continuations-in-part, reviews and re-examinations thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to said ASSIGNEE, for its interest as ASSIGNEE; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

and the undersigned hereby agree to transfer a like interest, to render all necessary assistance in making application for and obtaining original, extended, divisional, reissued, substituted, renewed, continued, continued-in-part, reviewed and re-examined Letters Patent of the United States, upon request of said ASSIGNEE and without further remuneration, in and to any improvements and applications for patent based thereon, growing out of or related to said invention, and to execute any papers by or for said

ASSIGNEE, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the dates indicated aside our signatures:

INVENTORS	DATE SIGNED
1) <u>Bernhard STERING</u>	<u>73. Dec. 2016</u>
2) <u>Name:</u>	<u></u>
3) <u>Name:</u>	<u></u>
4) <u>Name:</u>	<u></u>
5) <u>Name:</u>	<u></u>
6) <u>Name:</u>	<u></u>